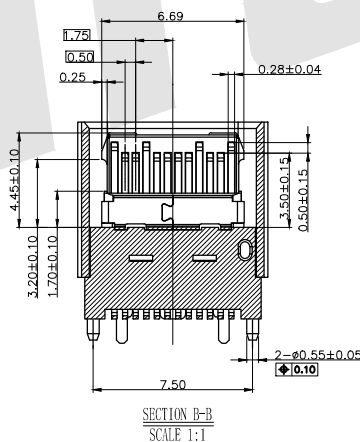
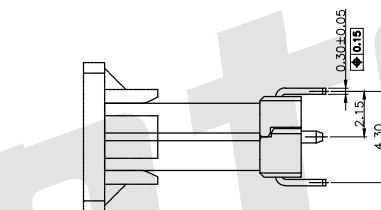
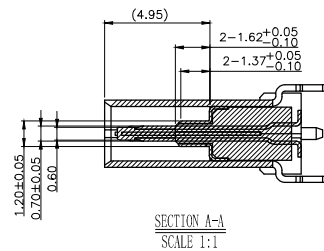
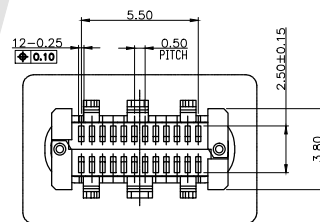
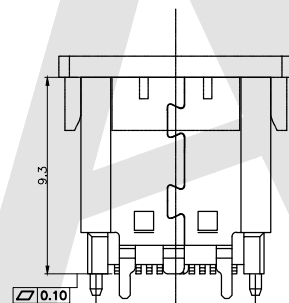
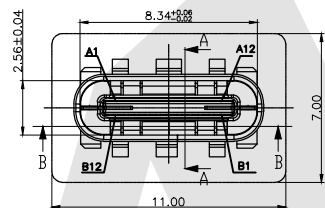
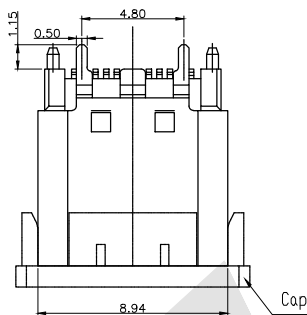


HSF



SPECIFICATIONS:

1. Electrical:
 - 1.1 Current Rating: 0.5A MIN For VBUS, 0.25A Min For Other
 - 1.2 Contact Resistance: 40 Milliohm Max.
 - 1.3 Dielectric Withstanding Voltage: 100V AC AT Sea Level
 - 1.4 Insulation Resistance: 100 Megohms Min.
2. Material:
 - 2.1 Housing: LCP, Glass Fiber Filled, Black
 - 2.2 Contact: Copper Alloy
 - 2.3 Guard Plate: Stainless Steel, T=0.10mm
 - 2.4 Shield: Stainless Steel (t=0.30mm).
3. Finish:
 - 3.1 Contact: 30u" Gold Plating On Contact Area
120u" Min. Tin (Matte) Plating On Solder tails
Area 80u" Min. Nickel Underplating Over All
 - 3.2 Shell: Nickel Plating
4. Mechanical Characteristics:
 - 4.1 Mating Force: 5-20N Max.
 - 4.2 Unmating Force: 8-20N Min.
 - 4.3 Durability: 10000 Cycles

U3.1FM02 - S - L - X - X - X
 (1) (2) (3) (4) (5) (6)

- | | |
|-------------------------|---------------------|
| (1) Series No: | (5) Contact Plating |
| (2) Shell Material: | G0: Gold flash |
| S: stainless steel | G1: 3u" Gold |
| (3) Insulator Material: | G2: 5u" Gold |
| L: LCP | G3: 10u" Gold |
| (4) Contact Material: | G4: 15u" Gold |
| B: Brass | G5: 30u" Gold |
| P: phosphor copper | (6) Packing |
| | A: Tray |
| | B: Bag |
| | C: Tube |
| | D: Tape & Reel |

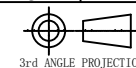
Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown	UNIT: mm
DRAW Lv Xun Hua	DATE 27/06/2019
CHECK BobYang	DATE 27/06/2019

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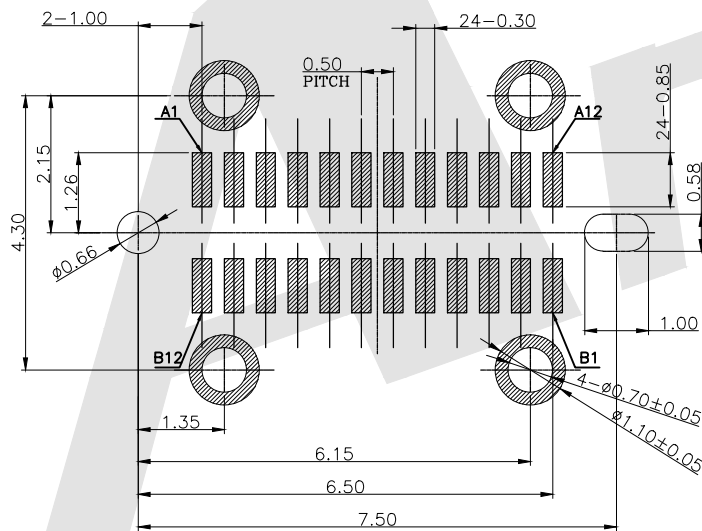
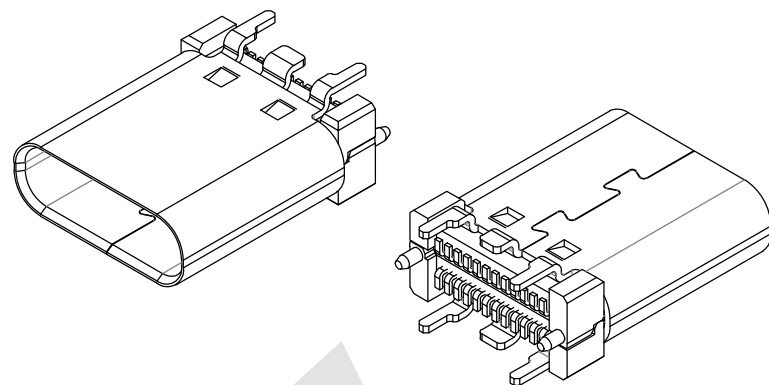
TITLE: USB3.1 C Type Receptacle Connector Vertical
 SMT With Four Shell Dip, With Post (H=9.50MM)

DRAWING NO: U3.1FM02-SLXXX
 PRODUCT NO: U3.1FM02-SLXXX



REV	DESCRIPTION	DATE

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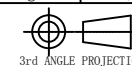
RECOMMENDED P.C.B. LAYOUT (T:1.00mm)
TOLERANCE UNSPECIFIED ±0.05mm

USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair
A4	VBUS	Bus Power	B9	VBUS	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use (SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use (SBU)	B5	CC2	Configuration Channel
A9	VBUS	Bus Power	B4	VBUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
DRAW Lv Xun Hua DATE 27/06/2019
CHECK BobYang DATE 27/06/2019



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TITLE: P.C.B LAYOUT

DRAWING NO: U3.1FM02-SLXXX

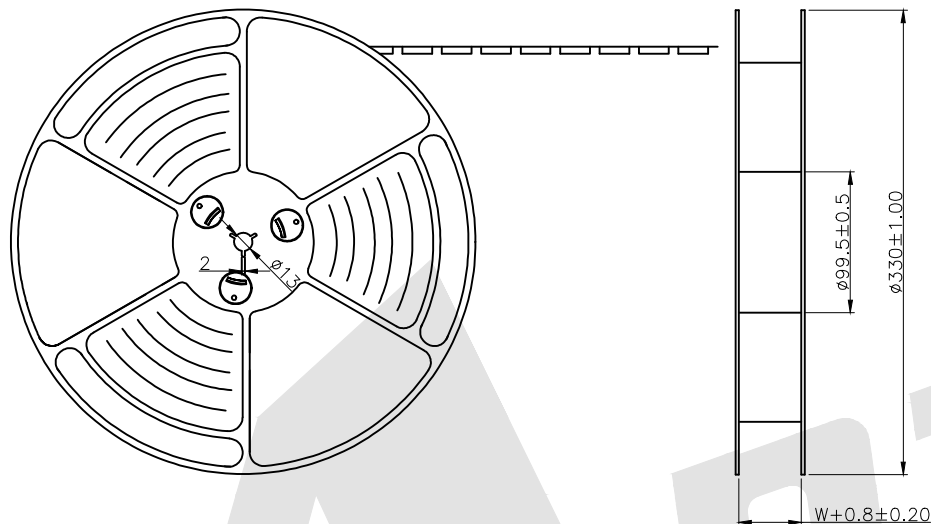
PRODUCT NO: U3.1FM02-SLXXX

REV	DESCRIPTION	DATE

HSF

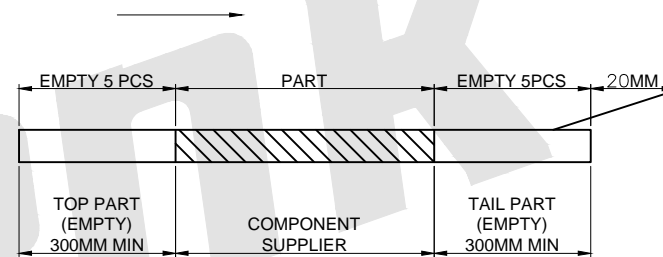


出料方向
PULL OUT DIRECTEON

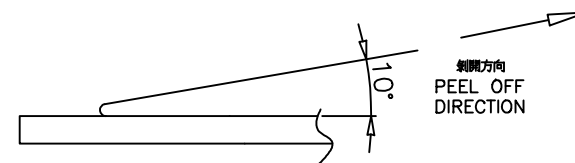
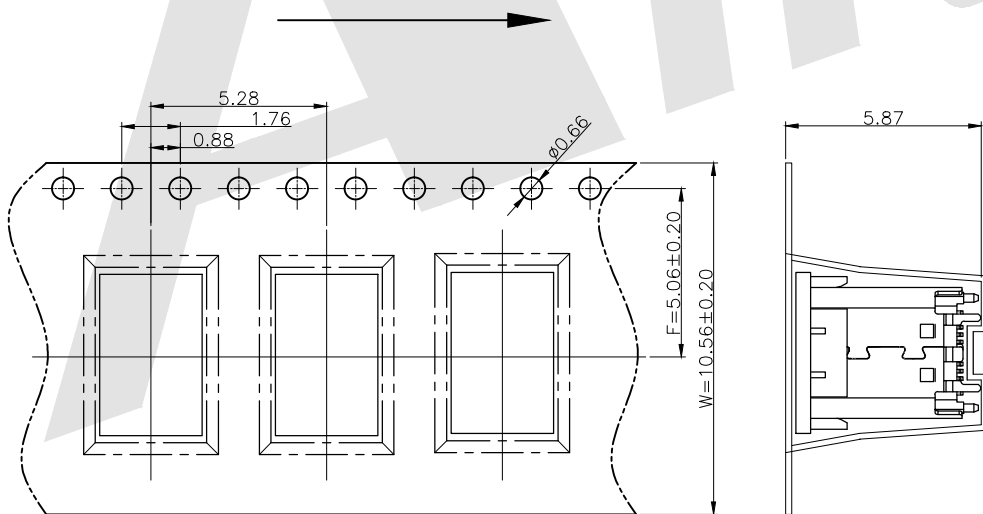


NOTES

1.帶子引導長度
LEAD TAPE LENGTH
出料方向
PULL OUT DIRECTEON



2.上帶 剝力力為：0.1~1.3N(10.2gf~130gf)
PEELING OFF FORCE OF TOP TAPE:0.1~1.3N(10.2gf~130gf)
出貨運輸過程中一定注意：
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT：
卷帶在運輸過程中不能散開
PEELING OFF SHOULD NOT BE ALLOWED DURING TRANSPORTATION



Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

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TITLE: Packing

DRAWING NO: U3.1FM02-SLXXX

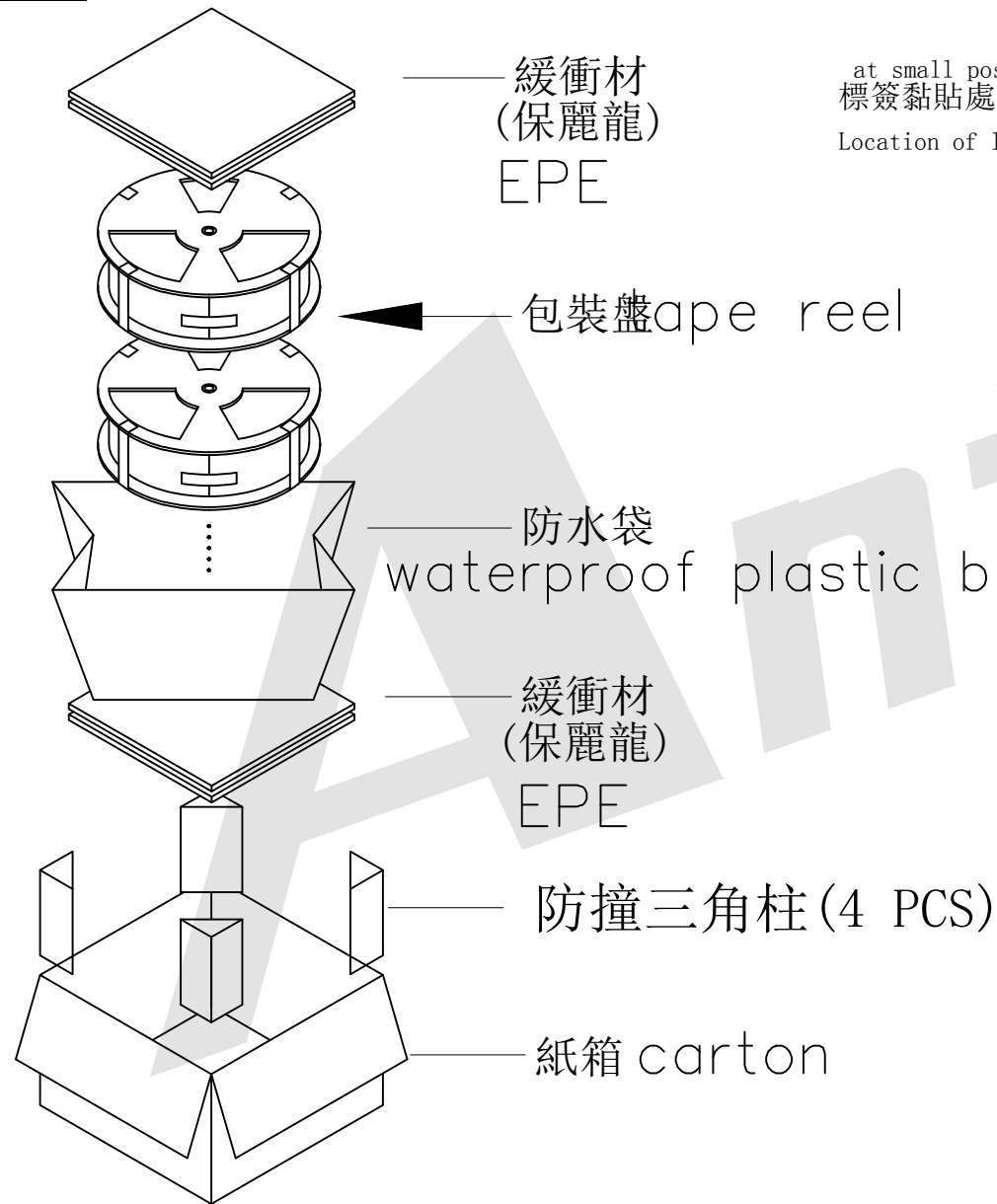
PRODUCT NO: U3.1FM02-SLXXX



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		

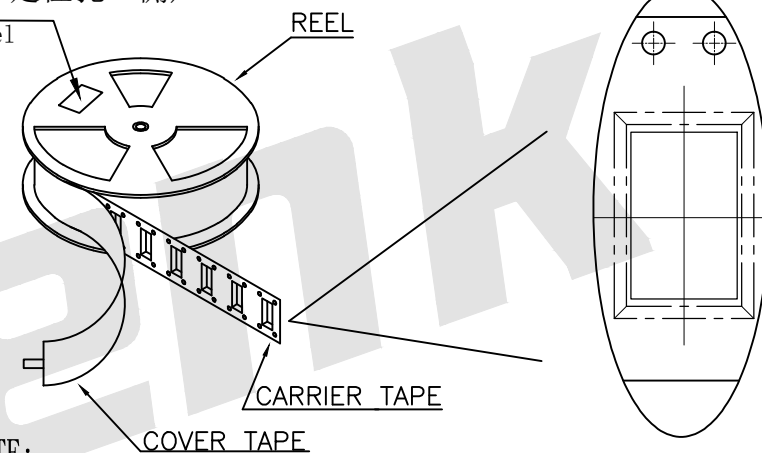
HSF

RoHS



at small positioning hole of the carrier tape side).
 標籤黏貼處 (朝捲裝包材的小定位孔一側)

Location of label sticking (label



NOTE:

1. 每捲包裝數量及每箱裝箱數量如左下表格。
Packing q'ty of each reel & carton as below table shown.
2. 以上膠帶覆蓋下包裝帶經包裝機熱熔包裝
Use cover tape to cover and hot melt machine to seal up.
3. 每個紙箱放2個珍珠棉
Every carton use 2pcs EPE.
4. 將裝滿產品的卷盤放入紙箱并以膠帶封口
Put reels in the carton and use adhesive tape to seal up.

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 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15



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TITLE: Packing
DRAWING NO: U3.1FM02-SLXXX
PRODUCT NO: U3.1FM02-SLXXX



REV	DESCRIPTION	DATE